

**CHIP PACKAGE WITH DIE AND SUBSTRATE**

Appl. No. : 10/055,568 Confirmation No. 6093  
Applicant : Mou-Shiung Lin,  
Jin-Yuan Lee,  
Ching-Cheng Huang  
Filed : January 22, 2002  
TC/A.U. : 2813  
Examiner : Mitchell, James M  
Docket No. : MEGP0004USA  
Customer No. : 27765

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**RESPONSE TO NON-FINAL OFFICE ACTION**

Sir:

- 5 The Non-Final Office Action mailed Mar. 13, 2007 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

- 10 **Remarks/Arguments** begin on page 7 of this paper.